

## FORTRON<sup>®</sup> 6150T4

### Polyphenylene sulfide

Fortron 6150T4 is a 50% glass-fiber reinforced and mineral-filled grade with improved impact and thermal shock resistance.

Product information Resin Identification Part Marking Code	PPS-I-(GF+MD)50 >PPS-I-(GF+MD)		ISO 1043 ISO 11469
Rheological properties Moulding shrinkage, parallel Moulding shrinkage, normal	0.2 0.5		ISO 294-4, 2577 ISO 294-4, 2577
Typical mechanical properties Tensile modulus Tensile stress at break, 5mm/min Tensile strain at break, 5mm/min Flexural modulus Flexural strength Charpy impact strength, 23°C Charpy notched impact strength, 23°C Poisson's ratio [C]: Calculated	1.7 15500 260 50	MPa %	ISO 527-1/-2 ISO 527-1/-2 ISO 527-1/-2 ISO 178 ISO 178 ISO 179/1eU ISO 179/1eA
Thermal properties Melting temperature, 10°C/min Glass transition temperature, 10°C/min Temperature of deflection under load, 1.8 MPa Coefficient of linear thermal expansion (CLTE), parallel Coefficient of linear thermal expansion (CLTE), normal		°C	ISO 11357-1/-3 ISO 11357-1/-3 ISO 75-1/-2 ISO 11359-1/-2 ISO 11359-1/-2
Flammability Burning Behav. at 1.5mm nom. thickn. Thickness tested Glow Wire Flammability Index, 1.0mm Glow Wire Flammability Index, 2.0mm Glow Wire Ignition Temperature, 1.0mm Glow Wire Ignition Temperature, 2.0mm [OT]: One time tested [1]: SR 01407577   Case   Salesforce 24COR032B _Glow Wire	1.5 960 <sup>[OT, 1]</sup> 960 <sup>[OT, 1]</sup> 775 <sup>[OT, 1]</sup> 825 <sup>[OT, 1]</sup>	°C °C	IEC 60695-11-10 IEC 60695-11-10 IEC 60695-2-12 IEC 60695-2-12 IEC 60695-2-13 IEC 60695-2-13
Electrical properties Relative permittivity, 1000Hz Relative permittivity, 1MHz Dissipation factor, 1000Hz Dissipation factor, 1MHz		E-4 E-4	IEC 62631-2-1 IEC 62631-2-1 IEC 62631-2-1 IEC 62631-2-1

Printed: 2025-05-30

(+) **18816996168** Ponciplastics.com



Sim. to ISO 62 ISO 1183

# FORTRON<sup>®</sup> 6150T4

### Polyphenylene sulfide

### Physical/Other properties

Water absorption, 2mm		0.02	0/_
•			
Density		1720	kg/m³
Injection			
Drying Recommended		yes	
Drying Temperature		130	°C
Drying Time, Dehumidified Dryer		2 - 4	h
Processing Moisture Content		≤0.02	%
Melt Temperature Optimum		330	°C
Min. melt temperature		310	°C
Max. melt temperature		340	°C
Screw tangential speed		0.2 - 0.3	m/s
Mold Temperature Optimum		150	°C
Min. mould temperature		140	°C
Max. mould temperature		160	°C
Hold pressure range		30 - 70	MPa
Back pressure		3	MPa
Characteristics			
Dressesian	lucia ationa Manulalina a		

Processing	Injection Moulding
Delivery form	Pellets
Special characteristics	High impact or impact modified, Thermal shock resistant

Printed: 2025-05-30

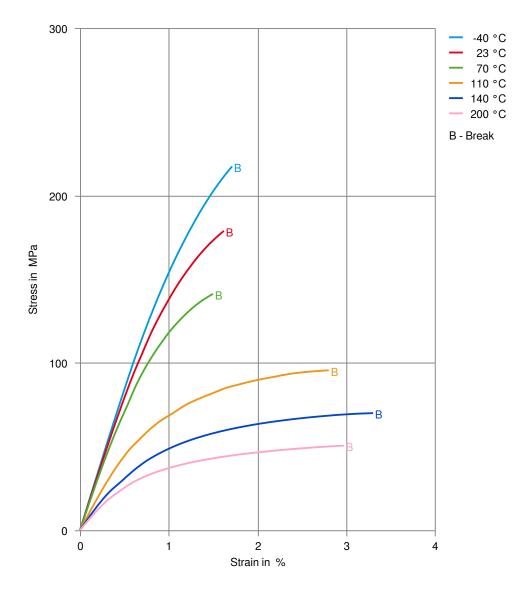




# FORTRON<sup>®</sup> 6150T4

## Polyphenylene sulfide

#### Stress-strain



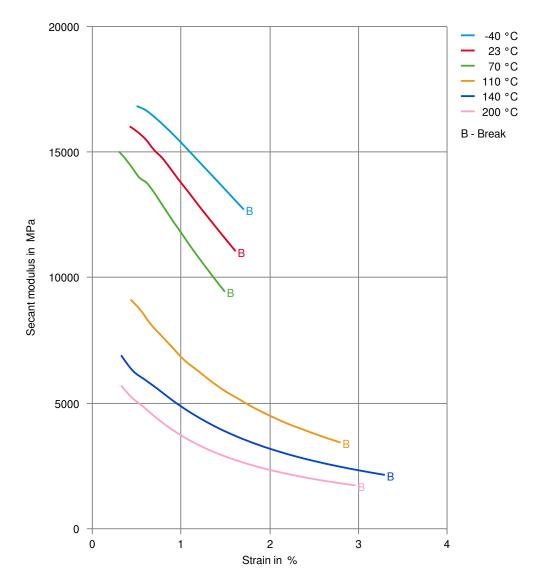




# FORTRON<sup>®</sup> 6150T4

### Polyphenylene sulfide

#### Secant modulus-strain



#### Printed: 2025-05-30

Page: 4 of 4

#### Revised: 2025-01-08 Source: Celanese Materials Database

NOTICE TO USERS: Values shown are based on testing of laboratory test specimens and represent data that fall within the standard range of properties for natural material. These values alone do not represent a sufficient basis for any part design and are not intended for use in establishing maximum, minimum, or ranges of values for specification purposes. Colourants or other additives may cause significant variations in data values. Properties of moulded parts can be influenced by a wide variety of factors including, but not limited to, material selection, additives, part design, processing conditions and environmental exposure. Other than those products expressly identified as medical grade (including by MT® product designation or otherwise), Celanese's products are not intended for use in medical or dental implants. Regardless of any such product designation, any determination of the suitability of a particular material and part design for any use contemplated by the users and the manner of such use is the sole responsibility of the users, who must assure themselves that the material as subsequently processed meets the needs of their particular product or use. To the best of our knowledge, the information contained in this publication is accurate; however, we do not assume any liability whatsoever for the accuracy and completeness of such information. Contained in this publication is accurate; however, we do not assume any liability of the dusers to investigate whether any existing patents are infringed by the use of the materials mentioned in this publication. Moreover, there is a need to reduce human exposure to many materials to the lowest practical limits in view of possible adverse effects. To the extent that any hazards may have been mentioned in this publication, we neither suggest nor guarantee that such hazards are the only ones that exist. We recommend that persons intending to rely on any recommendation or to use any equipment, processing technique or material industion for handling each material th

© 2025 Celanese or its affiliates. All rights reserved. Celanese®, registered C-ball design and all other trademarks identified herein with ®, TM, SM, unless otherwise noted, are trademarks of Celanese or its affiliates. Fortron is a registered trademark of Fortron Industries LLC.